

Material Composition Declaration

iS20M5R5S1TC

Company Name:	iDEAL Semiconductor Devices, Inc.
Quality Contact:	Deo Laranang
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Part Weight:	846.338 mg

Material	Composition	CAS No.	% of weight	Weight (mg)
Wafer	Silicon	7440-21-3	100	2
Leadframe	Cu	7440-50-8	Rem	503.6
	Fe	7439-89-6	0.05-0.15%	
	P	7723-14-0	0.025-0.04%	
	Ni	7723-14-0	0.01-0.03%	
Solder	Pb	7439-92-1	87.9 - 95.5	20.31
	Sn	7440-31-5	2 - 10	
	Ag	7440-22-4	1.5 - 2.6	
Wire	Al	7429-90-5	>99.99	5.448
	Other	7440-02-0	<0.01	
	Al	7429-90-5	99%±0.15%	
	Si	7440-21-3	1%±0.15%	
	Ni	7440-02-0	<60PPM	
	Other	-	<15PPM	
Mold Compound	Epoxy Resin	Trade Secret	5-10%	300.27
	Phenol resin	Trade Secret	1-5%	
	Silica A	60676-86-0	70-90%	
	Silica B	7631-86-9	10-20%	
	Carbon Black	1333-86-4	0.1-1%	
Plating	Sn	7440-31-5	>99.99	14.71
Total Weight				846.338

Note: The substance content disclosed herewith is approximate and is based on engineering calculations. Statements are based on our present knowledge and may be subject to change at any time due to technical requirements and development. iDEAL Semiconductor may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.